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TO-220AB

PRODUCT SUMMARY

V_{DS} (V)

R_{DS(on)} (Ω)

Q_{gs} (nC)

Q_{gd} (nC)

Q_a max. (nC)

Configuration

Power MOSFET

D FEATURES Q • Dynamic dV

S

N-Channel MOSFET

11

1000

38

4.9

22

Single

V_{GS} = 10 V

- Dynamic dV/dt rating
- Repetitive avalanche rated
- Fast switching
- Ease of paralleling
- Simple drive requirements
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

Note

* This datasheet provides information about parts that are RoHS-compliant and / or parts that are non RoHS-compliant. For example, parts with lead (Pb) terminations are not RoHS-compliant. Please see the information / tables in this datasheet for details

DESCRIPTION

Third generation power MOSFETs from Vishay provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The TO-220AB package is universally preferred for all commercial-industrial applications at power dissipation levels to approximately 50 W. The low thermal resistance and low package cost of the TO-220AB contribute to its wide acceptance throughout the industry.

ORDERING INFORMATION			
Package	TO-220AB		
Lead (Pb)-free	IRFBG20PbF		
Lead (Pb)-free and halogen-free	IRFBG20PbF-BE3		

PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-source voltage			V _{DS}	1000	- v	
Gate-source voltage			V _{GS}	± 20		
Continuous drain current	V _{GS} at 10 V	$T_{\rm C} = 25 \ ^{\circ}{\rm C}$ $T_{\rm C} = 100 \ ^{\circ}{\rm C}$		1.4		
		T _C = 100 °C	ID	0.86	А	
Pulsed drain current ^a			I _{DM}	5.6	1	
Linear derating factor				0.43	W/°C	
Single pulse avalanche energy ^b			E _{AS}	200	mJ	
Repetitive avalanche current ^a			I _{AR}	1.4	А	
Repetitive avalanche energy ^a			E _{AR}	5.4	mJ	
Maximum power dissipation	T _C = 25 °C		PD	54	W	
Peak diode recovery dV/dt ^c			dV/dt	1.0	V/ns	
Operating junction and storage temperature range		T _J , T _{stg}	-55 to +150	°C		
Soldering recommendations (peak temperature) ^d	For 10 s			300		
Mounting torque	6-32 or M3 screw			10	lbf · in	
				1.1	N · m	

Notes

a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11)

b. V_{DD} = 50 V, starting T_J = 25 °C, L = 193 µH, R_g = 25 Ω , I_{AS} = 1.4 A (see fig. 12)

c. $I_{SD} \le 1.4$ A, dI/dt ≤ 60 A/µs, $V_{DD} \le 600$, $T_J \le 150$ °C

d. 1.6 mm from case

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THERMAL RESISTANCE RATINGS					
PARAMETER	SYMBOL	TYP.	MAX.	UNIT	
Maximum junction-to-ambient	R _{thJA}	-	62		
Case-to-sink, flat, greased surface	R _{thCS}	0.50	-	°C/W	
Maximum junction-to-case (drain)	R _{thJC}	-	2.3		

PARAMETER	SYMBOL TEST CONDITIONS		ST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Static							
Drain-source breakdown voltage	V _{DS}	V _{GS} :	= 0 V, I _D = 250 μA	1000	-	-	V
V _{DS} temperature coefficient	$\Delta V_{DS}/T_{J}$	Reference to 25 °C, $I_D = 1$ mA		-	1.2	-	V/°C
Gate-source threshold voltage	V _{GS(th)}	V _{DS} =	V _{DS} = V _{GS} , I _D = 250 μA		-	4.0	V
Gate-source leakage	I _{GSS}		$V_{GS} = \pm 20 V$		-	± 100	nA
Zero gate voltage drain current	lana	$V_{DS} = 1000 \text{ V}, V_{GS} = 0 \text{ V}$		-	-	100	μA
Zelo gate voltage drain current	I _{DSS}	V _{DS} = 800 V	$V_{DS} = 800 \text{ V}, V_{GS} = 0 \text{ V}, T_J = 125 ^{\circ}\text{C}$		-	500	
Drain-source on-state resistance	R _{DS(on)}	$V_{GS} = 10 V$	I _D = 0.84 A ^b	-	-	11	Ω
Forward transconductance	g _{fs}	V _{DS} =	50 V, $I_D = 0.84 \text{ A}^{\text{b}}$	1.0	-	-	S
Dynamic							
Input capacitance	C _{iss}		$V_{GS} = 0 V,$	-	500	-	
Output capacitance	C _{oss}	V _{DS} = 25 V,		-	52	-	pF
Reverse transfer capacitance	C _{rss}	f = 1	.0 MHz, see fig. 5	-	17	-	
Total gate charge	Qg		I _D = 1.4 A, V _{DS} = 400 V, see fig. 6 and 13 ^b	-	-	38	nC
Gate-source charge	Q _{gs}	$V_{GS} = 10 V$		-	-	4.9	
Gate-drain charge	Q _{gd}			-	-	22	
Turn-on delay time	t _{d(on)}			-	9.4	-	
Rise time	t _r	- V _{DD} =	= 500 V, I _D = 1.4 A,	-	17	-	
Turn-off delay time	t _{d(off)}	$R_g = 18 \ \Omega$, $R_D = 370 \ \Omega$, see fig. 10 ^b		-	58	-	ns
Fall time	t _f			-	31	-	
Internal drain inductance	L _D	Between lead, 6 mm (0.25") from package and center of die contact		-	4.5	-	nH
Internal source inductance	L _S			-	7.5	-	
Gate input resistance	R _g	f = 1 MHz, open drain		0.6	-	3.4	Ω
Drain-Source Body Diode Characteristic	cs	·					
Continuous source-drain diode current	IS	MOSFET symbol showing the integral reverse p - n junction diode		-	-	1.4	A
Pulsed diode forward current ^a	I _{SM}			-	-	5.6	
Body diode voltage	V _{SD}	$T_{\rm J}$ = 25 °C, $I_{\rm S}$ = 1.4 A, $V_{\rm GS}$ = 0 V ^b		-	-	1.5	V
Body diode reverse recovery time	t _{rr}	$T_J = 25 \text{ °C}, I_F = 1.4 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}^{\text{ b}}$		-	130	190	ns
Body diode reverse recovery charge	Q _{rr}			-	0.46	0.69	μC
Forward turn-on time	t _{on}	Intrinsic tu	ırn-on time is negligible (turn	-on is dor	ninated b	y L _S and	L _D)

Notes

a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11)

b. Pulse width \leq 300 µs; duty cycle \leq 2 %

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TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

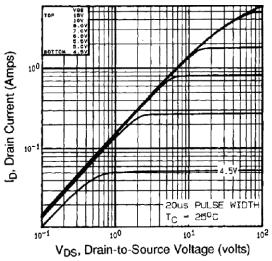


Fig. 1 - Typical Output Characteristics, T_C = 25 °C

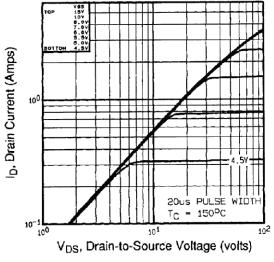


Fig. 2 - Typical Output Characteristics, $T_C = 150 \ ^\circ C$

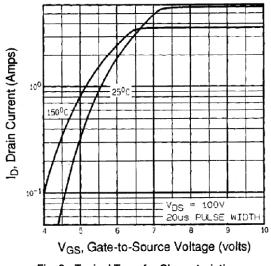


Fig. 3 - Typical Transfer Characteristics

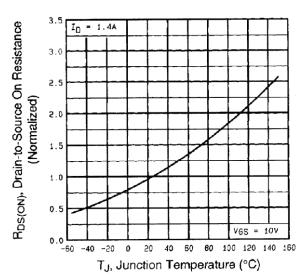


Fig. 4 - Normalized On-Resistance vs. Temperature



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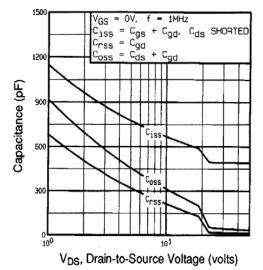


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

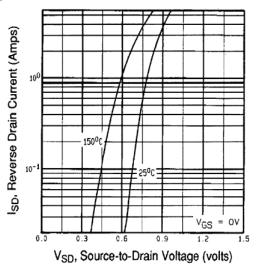


Fig. 7 - Typical Source-Drain Diode Forward Voltage

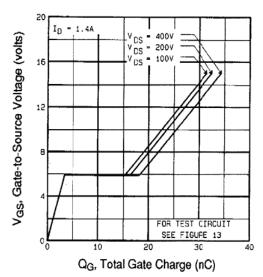
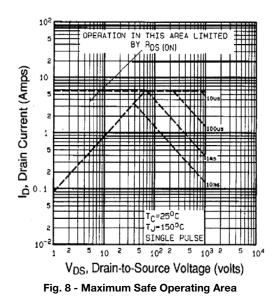


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage



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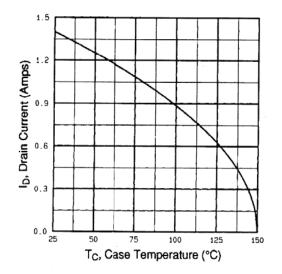


Fig. 9 - Maximum Drain Current vs. Case Temperature

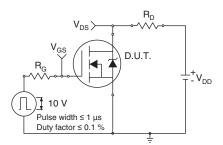


Fig. 10a - Switching Time Test Circuit

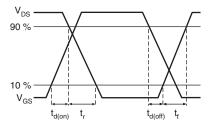
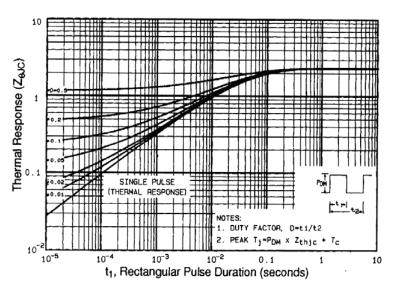


Fig. 10b - Switching Time Waveforms





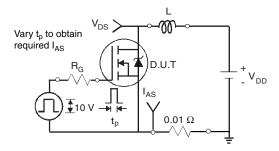


Fig. 12a - Unclamped Inductive Test Circuit

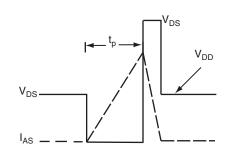


Fig. 12b - Unclamped Inductive Waveforms

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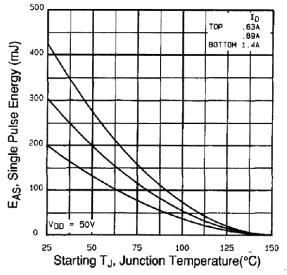


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

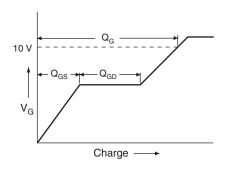


Fig. 13a - Basic Gate Charge Waveform

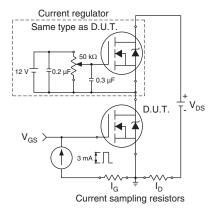


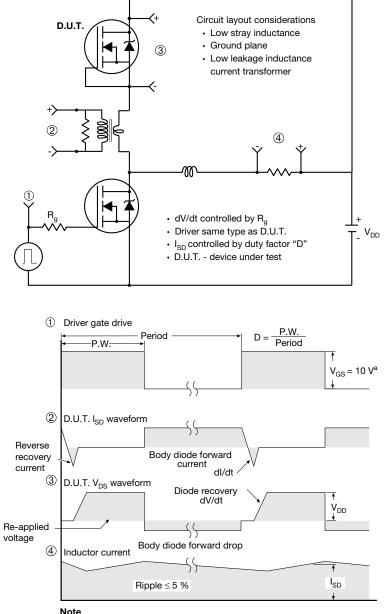
Fig. 13b - Gate Charge Test Circuit

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Peak Diode Recovery dV/dt Test Circuit



a. $V_{GS} = 5$ V for logic level devices

Fig. 14 - For N-Channel

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